



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Steinmann et al.

Art Unit: 1765

Serial No.: 09/852,921

Examiner: Deo, D.

Filing Date: 05/10/2001

Docket No.: TI-29881

Customer No.: 23494

Conf. No.: 5844

Title: METHOD OF INTEGRATING A THIN FILM RESISTOR IN A MULTI-LEVEL
METAL TUNGSTEN-PLUG INTERCONNECT

LETTER OF TRANSMITTAL

Commissioner of Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that the above correspondence is being
deposited with the U.S. Postal Service as First Class Mail
in an envelope addressed to: Commissioner of Patents,
P. O. Box 1450, Alexandria, VA 22313-1450

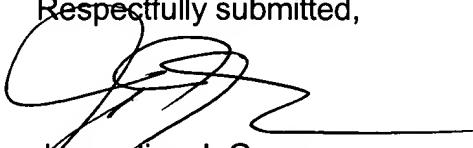
3-5-04
Date

Marianna Smith
Marianna Smith

Enclosed please find the signed Supplemental Declaration in the above-identified
application.

Please charge any necessary fee to Deposit Account No. 20-0668.

Respectfully submitted,


Jacqueline J. Garner
Attorney for Applicants
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